

SOT-563 20V Dual N Channel Enhancement with ESD 双N沟道增强型带静电保护 MOS Field Effect Transistor 场效应管

■ Features 特点

Low on-resistance 低导通电阻

$R_{DS(ON)}=200\text{m}\Omega$ (Type)@ $V_{GS}=4.5\text{V}$

$R_{DS(ON)}=235\text{m}\Omega$ (Type)@ $V_{GS}=2.5\text{V}$

$R_{DS(ON)}=295\text{m}\Omega$ (Type)@ $V_{GS}=1.8\text{V}$

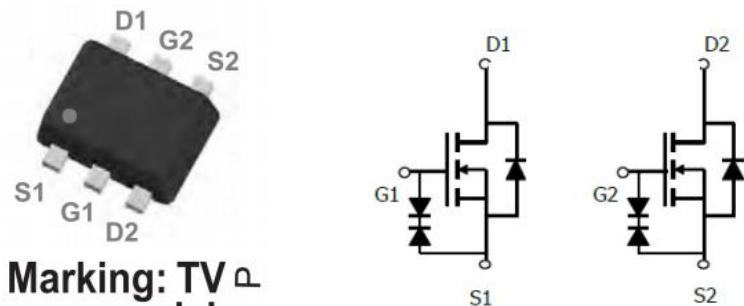
■ Applications 应用

Hand-held Equipment 手持设备

Load Switch & Networking 负载开关和网络

Power Management in Note Book 笔记本电源管理

■ Internal Schematic Diagram 内部结构



■ Absolute Maximum Ratings 最大额定值

Characteristic 特性参数	Symbol 符号	Rating 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	20	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	± 8	V
Drain Current (continuous)漏极电流-连续	I_D (at $T_A = 25^\circ\text{C}$) (at $T_A = 25^\circ\text{C}$)	800 640	mA
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	3.2	A
Total Device Dissipation 总耗散功率	P_D (at $T_A = 25^\circ\text{C}$)	312	mW
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JA}$	400	$^\circ\text{C}/\text{W}$
Junction/Storage Temperature 结温/储存温度	T_J, T_{stg}	-55~150	°C



安徽富信半导体科技有限公司

ANHUI FOSAN SEMICONDUCTOR TECHNOLOGY CO., LTD.

DMN2400UV

■ Electrical Characteristics 电特性

($T_A=25^\circ\text{C}$ unless otherwise noted 如无特殊说明, 温度为 25°C)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压($I_D=250\mu\text{A}, V_{GS}=0\text{V}$)	BV_{DSS}	20	—	—	V
Gate Threshold Voltage 栅极开启电压($I_D=250\mu\text{A}, V_{GS}=V_{DS}$)	$V_{GS(\text{th})}$	0.3	0.6	1.0	V
Zero Gate Voltage Drain Current 零栅压漏极电流($V_{GS}=0\text{V}, V_{DS}=20\text{V}$)	I_{DSS}	—	—	1	μA
Gate Body Leakage 栅极漏电流($V_{GS}=\pm 8\text{V}, V_{DS}=0\text{V}$)	I_{GSS}	—	—	± 10	μA
Static Drain-Source On-State Resistance 静态漏源导通电阻($I_D=0.5\text{A}, V_{GS}=4.5\text{V}$) ($I_D=0.4\text{A}, V_{GS}=2.5\text{V}$) ($I_D=0.2\text{A}, V_{GS}=1.8\text{V}$)	$R_{DS(\text{ON})}$	—	200 235 295	300 400 550	$\text{m}\Omega$
Diode Forward Voltage Drop 内附二极管正向压降($I_{SD}=0.3\text{A}, V_{GS}=0\text{V}$)	V_{SD}	—	—	1.2	V
Input Capacitance 输入电容 ($V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$)	C_{ISS}	—	38	—	pF
Common Source Output Capacitance 共源输出电容($V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$)	C_{OSS}	—	15	—	pF
Reverse Transfer Capacitance 反馈电容 ($V_{GS}=0\text{V}, V_{DS}=10\text{V}, f=1\text{MHz}$)	C_{RSS}	—	6	—	pF
Total Gate Charge 棚极电荷密度 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, V_{GS}=4.5\text{V}$)	Q_g	—	1	—	nC
Gate Source Charge 棚源电荷密度 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, V_{GS}=4.5\text{V}$)	Q_{gs}	—	0.26	—	nC
Gate Drain Charge 棚漏电荷密度 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, V_{GS}=4.5\text{V}$)	Q_{gd}	—	0.2	—	nC
Turn-ON Delay Time 开启延迟时间 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$)	$t_{d(\text{on})}$	—	5	—	ns
Turn-ON Rise Time 开启上升时间 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$)	t_r	—	5	—	ns
Turn-OFF Delay Time 关断延迟时间 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$)	$t_{d(\text{off})}$	—	15	—	ns
Turn-OFF Fall Time 关断下降时间 ($V_{DS}=10\text{V}, I_D=0.5\text{A}, R_{\text{GEN}}=10\Omega, V_{GS}=4.5\text{V}$)	t_f	—	6	—	ns

■ Typical Characteristic Curve 典型特性曲线

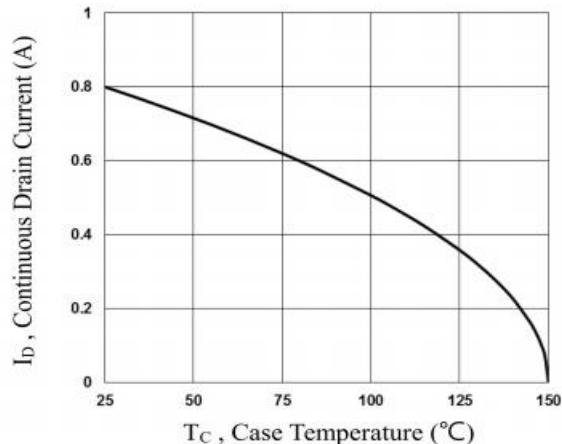


Figure 1: Drain Current vs. Temperature

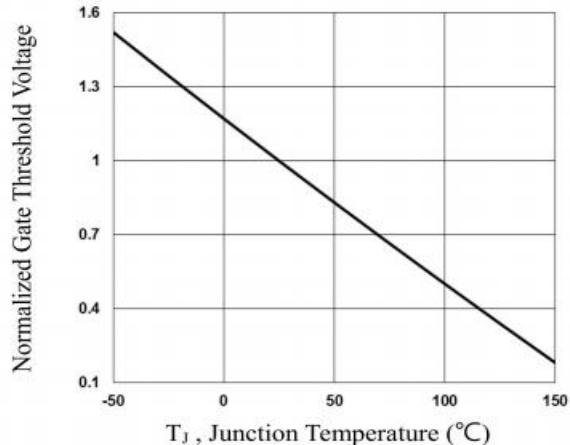


Figure 3: Threshold Voltage vs. Temperature

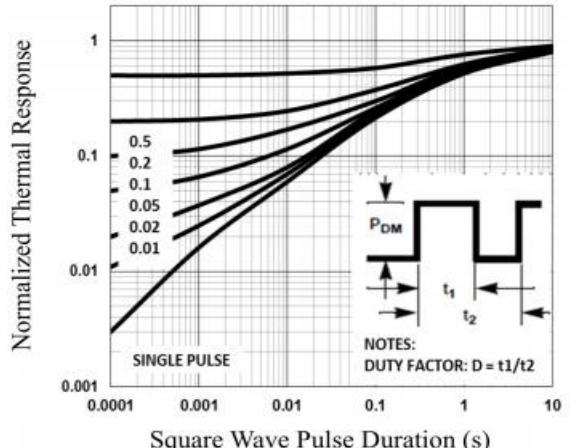


Figure 5: Transient Thermal Response Curve

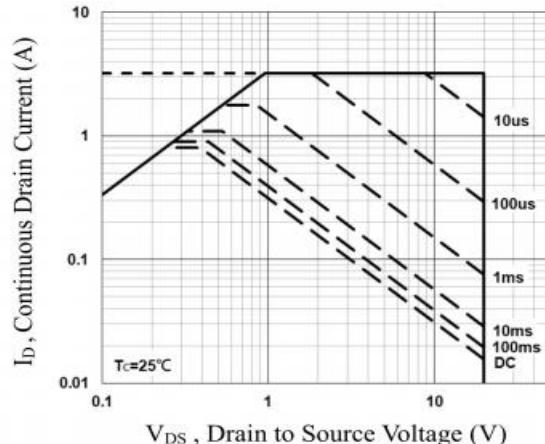


Figure 2: Safe Operating Area

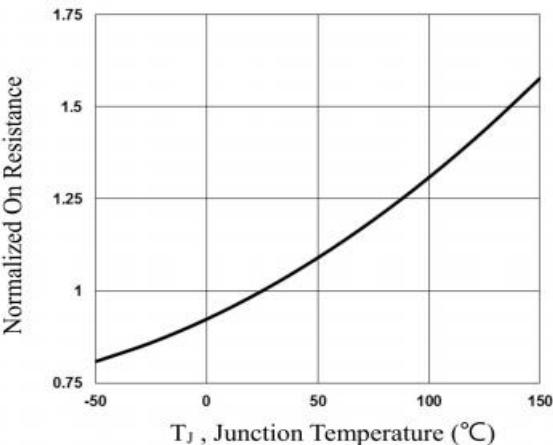


Figure 4: On-Resistance vs. Temperature

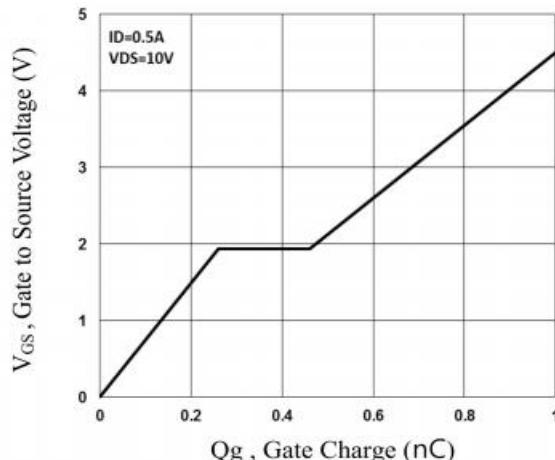
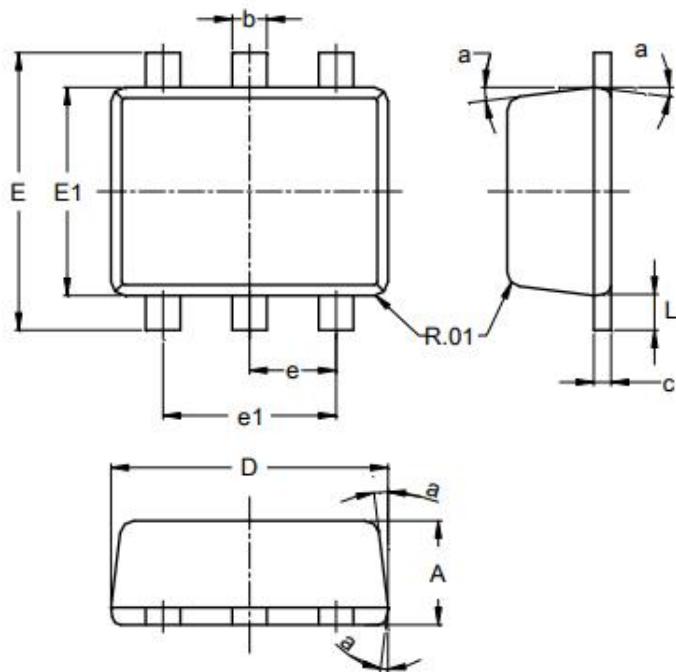


Figure 6: Gate-Charge Characteristics

■ Dimension 外形封装尺寸



Dim	Min	Max	Typ
A	0.55	0.60	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.11
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	--	--	0.50
e1	0.90	1.10	1.00
L	0.10	0.30	0.20
a	8°	9°	7°

All Dimensions in mm